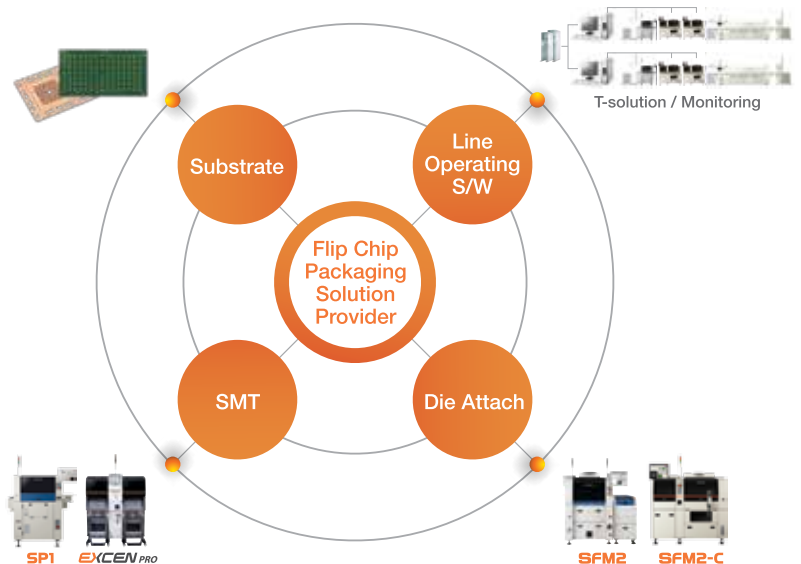


## Compact High Speed Flip Chip Mounter

# SFM2-C

### Realizes The World's Highest Productivity

The SFM2-C, a flip chip mounter consisting of one gantry structures with four spindles per head, allows the maximum 20N current force control with 0.1N resolution and the precision touch recognition function using a high-performance linear motor controller. It realizes the world's highest productivity of 6,800 UPH. In addition, it achieves a placement accuracy of  $\pm 8\mu\text{m}$  @ $3\sigma$  by applying a precision motor control system to the XY gantry.



- Max 6,800 UPH(Optimum)
- 4 Spindles/Head x 1 Gantry
- Accuracy :  $\pm 8\mu\text{m}$  @ $3\sigma$
- Die Size :  $\square 0.5 \sim 32\text{mm}$
- Wafer Size : 6, 8, 12"
- Bump Pitch : Min. 50 $\mu\text{m}$
- Substrate Size : Max. 330(L) x 225(W)
- Waffle Tray Feeder(Optional)

Compact  
High Speed Flip Chip Mounter

# SFM2-C



## Enhanced Vision Performance

- Wide and clear view(FOV : □ 15mm)
- Detection of bump defects in advance
- Stable wafer alignment



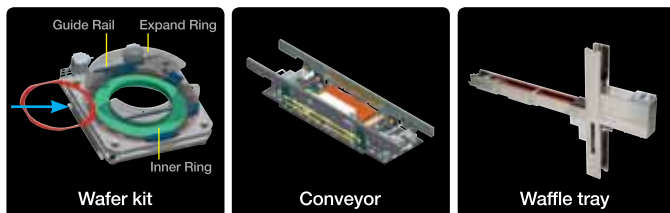
## Bond Head

- Fine bond force control
- Low impact
- Real time touch detection



## Flexibility

- Easy & quick conversion(6, 8, 12")
- Wide substrate coverage(330 x 225mm)
- Waffle tray feeding available(Optional)
- Die coverage : □ 0.5~32mm



## High UPH

- Single-gantry system, 4 spindles/gantry
- 4 turret flippers
- 2 die transfer shuttles, 4 units/shuttle



## Fluxer Stability

- Zero defect
- No Flux shortage or leakage



Model		SFM2-C
UPH		Max. 6.8K
Placement Accuracy		±8μm @3σ
Substrate	Width	50 ~ 225mm
	Length	50 ~ 330mm
	Thickness	0.2 ~ 4.0mm
Die	Size	□ 0.5 ~ □ 32mm
	Thickness	Min. 80μm
Wafer		6", 8, 12"
Bump	Pitch	Min. 70μm(50μm @FOV10)
	Diameter	50 ~ 500μm(30μm @FOV10)
	Height	30 ~ 300μm
Flux	Thickness	Min. 15μm
	Fluxing Accuracy	±5μm
	Flux Tank Capacity	40cc
Bond Force		Max. 20N
Dimension		1,650(L) x 1,560(W)mm
Utility	Power	Max. 5.6 ~ 6.8Kwh
	Compressed Air	0.55 MPa <sup>1</sup>
	Electricity	AC 200~480V, 50/60Hz, 3-Phase

<sup>1</sup> Optional with 8" ring

SAMSUNG

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• The dimensions and product specifications in this catalog may be changed without prior notice.